

#### -100 Volt, 0.60Ω HEXFET

HEXFET technology is the key to International Rectifier's advanced line of power MOSFET transistors. The efficient geometry achieves very low on-state resistance combined with high transconductance.

HEXFET transistors also feature all of the well-established advantages of MOSFETs, such as voltage control, very fast switching, ease of paralleling and electrical parameter temperature stability. They are well-suited for applications such as switching power supplies, motor controls, inverters, choppers, audio amplifiers, and high energy pulse circuits, and virtually any application where high reliability is required.

#### Product Summary

| Part Number  | BV <sub>DSS</sub> | R <sub>DS(on)</sub> | I <sub>D</sub> |
|--------------|-------------------|---------------------|----------------|
| JANTX2N6845  | -100V             | 0.60Ω               | -4.0A          |
| JANTXV2N6845 |                   |                     |                |

#### Features:

- Avalanche Energy Rating
- Dynamic dv/dt Rating
- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed

#### Absolute Maximum Ratings

|                                                                 | Parameter                   | JANTX2N6845, JANTXV2N6845                          | Units |
|-----------------------------------------------------------------|-----------------------------|----------------------------------------------------|-------|
| I <sub>D</sub> @ V <sub>GS</sub> = -10V, T <sub>C</sub> = 25°C  | Continuous Drain Current    | -4.0                                               | A     |
| I <sub>D</sub> @ V <sub>GS</sub> = -10V, T <sub>C</sub> = 100°C | Continuous Drain Current    | -2.6                                               |       |
| I <sub>DM</sub>                                                 | Pulsed Drain Current ①      | -16                                                |       |
| P <sub>D</sub> @ T <sub>C</sub> = 25°C                          | Max. Power Dissipation      | 20                                                 | W     |
|                                                                 | Linear Derating Factor      | 0.16                                               | W/K ⑤ |
| V <sub>GS</sub>                                                 | Gate-to-Source Voltage      | ±20                                                | V     |
| dv/dt                                                           | Peak Diode Recovery dv/dt ③ | -5.0                                               | V/ns  |
| T <sub>J</sub>                                                  | Operating Junction          | -55 to 150                                         | °C    |
| T <sub>STG</sub>                                                | Storage Temperature Range   |                                                    |       |
|                                                                 | Lead Temperature            | 300 (0.063 in. (1.6mm) from case for 10.5 seconds) |       |
|                                                                 | Weight                      | 0.98 (typical)                                     | g     |

## JANTX2N6845, JANTXV2N6845 Device

### Electrical Characteristics @ $T_j = 25^\circ\text{C}$ (Unless Otherwise Specified)

|                              | Parameter                                    | Min. | Typ.  | Max. | Units              | Test Conditions                                                                     |
|------------------------------|----------------------------------------------|------|-------|------|--------------------|-------------------------------------------------------------------------------------|
| $BV_{DSS}$                   | Drain-to-Source Breakdown Voltage            | -100 | —     | —    | V                  | $V_{GS} = 0V$ , $I_D = -1.0\text{ mA}$                                              |
| $\Delta BV_{DSS}/\Delta T_j$ | Temperature Coefficient of Breakdown Voltage | —    | -0.10 | —    | $V/^\circ\text{C}$ | Reference to $25^\circ\text{C}$ , $I_D = -1.0\text{ mA}$                            |
| $R_{DS(on)}$                 | Static Drain-to-Source On-State Resistance   | —    | —     | 0.60 | $\Omega$           | $V_{GS} = -10V$ , $I_D = -2.6A$ ④                                                   |
|                              |                                              | —    | —     | 0.69 |                    | $V_{GS} = -10V$ , $I_D = -4.0A$                                                     |
| $V_{GS(th)}$                 | Gate Threshold Voltage                       | -2.0 | —     | -4.0 | V                  | $V_{DS} = V_{GS}$ , $I_D = -250\mu A$                                               |
| $g_{fs}$                     | Forward Transconductance                     | 1.25 | —     | —    | S ( $\Omega$ )     | $V_{DS} > -15V$ , $I_{DS} = -2.6A$ ④                                                |
| $I_{DSS}$                    | Zero Gate Voltage Drain Current              | —    | —     | -25  | $\mu A$            | $V_{DS} = 0.8 \times \text{Max Rating}$ , $V_{GS} = 0V$                             |
|                              |                                              | —    | —     | -250 |                    | $V_{DS} = 0.8 \times \text{Max Rating}$ , $V_{GS} = 0V$ , $T_j = 125^\circ\text{C}$ |
| $I_{GSS}$                    | Gate-to-Source Leakage Forward               | —    | —     | -100 | nA                 | $V_{GS} = -20V$                                                                     |
| $I_{GSS}$                    | Gate-to-Source Leakage Reverse               | —    | —     | 100  |                    | $V_{GS} = 20V$                                                                      |
| $Q_g$                        | Total Gate Charge                            | 4.3  | —     | 16.3 | nC                 | $V_{GS} = -10V$ , $I_D = -4.0A$                                                     |
| $Q_{gs}$                     | Gate-to-Source Charge                        | 1.3  | —     | 4.7  |                    | $V_{DS} = \text{Max. Rating} \times 0.5$                                            |
| $Q_{gd}$                     | Gate-to-Drain ("Miller") Charge              | 1.0  | —     | 9.0  |                    | see figures 6 and 13                                                                |
| $t_{d(on)}$                  | Turn-On Delay Time                           | —    | —     | 60   | ns                 | $V_{DD} = -50V$ , $I_D = -4.0A$ ,<br>$R_G = 7.5\Omega$ , $V_{GS} = -10V$            |
| $t_r$                        | Rise Time                                    | —    | —     | 100  |                    |                                                                                     |
| $t_{d(off)}$                 | Turn-Off Delay Time                          | —    | —     | 50   |                    |                                                                                     |
| $t_f$                        | Fall Time                                    | —    | —     | 70   |                    |                                                                                     |
| $L_D$                        | Internal Drain Inductance                    | —    | 5.0   | —    | nH                 | Measured from the drain lead, 6mm (0.25 in.) from package to center of die.         |
| $L_S$                        | Internal Source Inductance                   | —    | 15    | —    |                    | Measured from the source lead, 6mm (0.25 in.) from package to source bonding pad.   |
| $C_{iss}$                    | Input Capacitance                            | —    | 380   | —    | pF                 | $V_{GS} = 0V$ , $V_{DS} = -25V$<br>$f = 1.0\text{ MHz}$<br>see figure 5             |
| $C_{oss}$                    | Output Capacitance                           | —    | 170   | —    |                    |                                                                                     |
| $C_{rss}$                    | Reverse Transfer Capacitance                 | —    | 45    | —    |                    |                                                                                     |

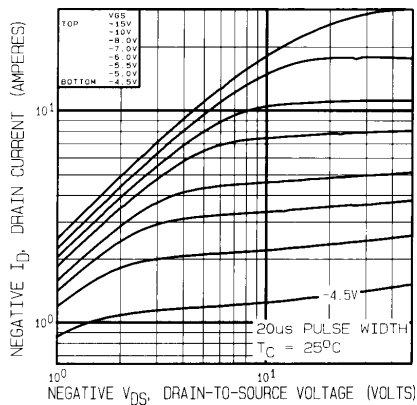
### Source-Drain Diode Ratings and Characteristics

|                 | Parameter                              | Min.                                                                                                                 | Typ. | Max. | Units | Test Conditions                                                                                                                                                   |
|-----------------|----------------------------------------|----------------------------------------------------------------------------------------------------------------------|------|------|-------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| I <sub>S</sub>  | Continuous Source Current (Body Diode) | —                                                                                                                    | —    | -4.0 | A     | Modified MOSFET symbol showing the integral reverse p-n junction rectifier.  |
| I <sub>SM</sub> | Pulse Source Current (Body Diode) ①    | —                                                                                                                    | —    | -16  |       |                                                                                                                                                                   |
| V <sub>SD</sub> | Diode Forward Voltage                  | —                                                                                                                    | —    | -4.8 | V     | T <sub>j</sub> = 25°C, I <sub>S</sub> = -4.0A, V <sub>GS</sub> = 0V ④                                                                                             |
| t <sub>rr</sub> | Reverse Recovery Time                  | —                                                                                                                    | —    | 200  | ns    | T <sub>j</sub> = 25°C, I <sub>F</sub> = -4.0A, di/dt ≤ -100A/μs<br>V <sub>DD</sub> ≤ -50V ④                                                                       |
| Q <sub>RR</sub> | Reverse Recovery Charge                | —                                                                                                                    | —    | 3.1  | μC    |                                                                                                                                                                   |
| t <sub>on</sub> | Forward Turn-On Time                   | Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by L <sub>S</sub> + L <sub>D</sub> . |      |      |       |                                                                                                                                                                   |

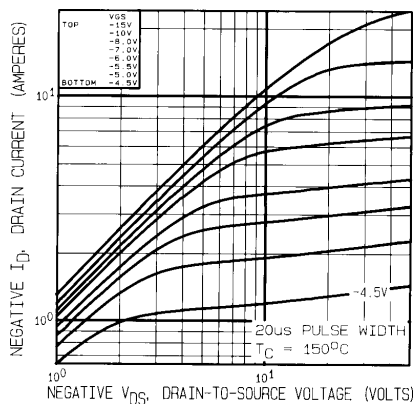
### Thermal Resistance

|            | Parameter           | Min. | Typ. | Max. | Units | Test Conditions      |
|------------|---------------------|------|------|------|-------|----------------------|
| $R_{thJC}$ | Junction-to-Case    | —    | —    | 6.25 | K/W   | Typical socket mount |
| $R_{thJA}$ | Junction-to-Ambient | —    | —    | 175  |       |                      |

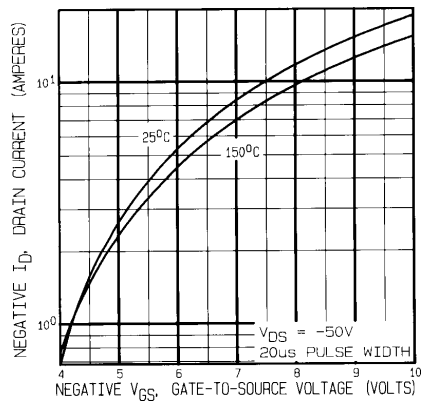
# JANTX2N6845, JANTXV2N6845 Device



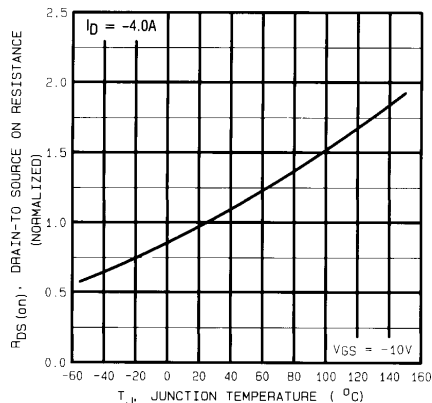
**Fig. 1 — Typical Output Characteristics**  
 $T_C = 25^\circ\text{C}$



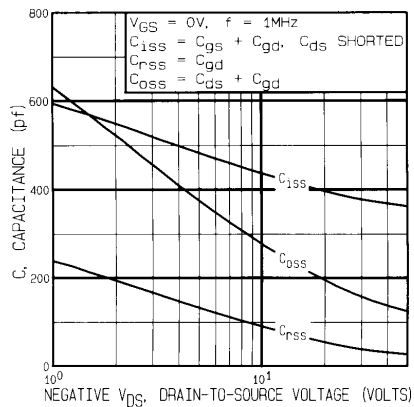
**Fig. 2 — Typical Output Characteristics**  
 $T_C = 150^\circ\text{C}$



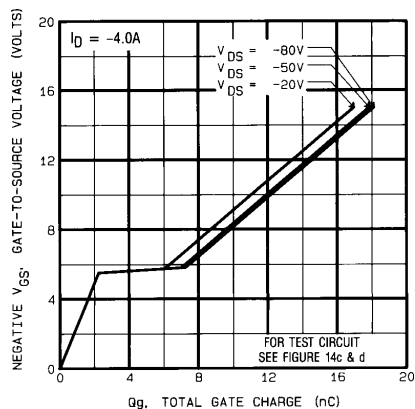
**Fig. 3 — Typical Transfer Characteristics**



**Fig. 4 — Normalized On-Resistance Vs. Temperature**



**Fig. 5 — Typical Capacitance Vs. Drain-to-Source Voltage**



**Fig. 6 — Typical Gate Charge Vs. Gate-to-Source Voltage**

JANTX2N6845, JANTXV2N6845 Device

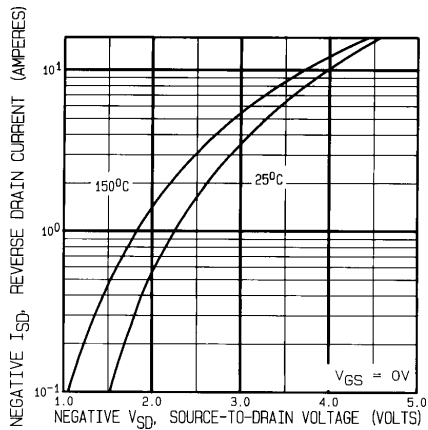


Fig. 7 — Typical Source-to-Drain Diode Forward Voltage

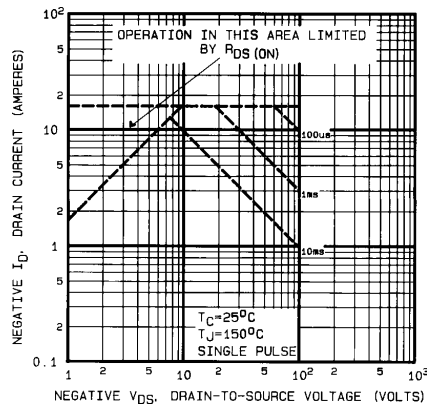


Fig. 8 — Maximum Safe Operating Area

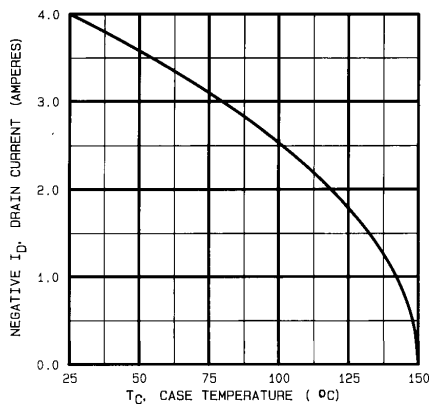


Fig. 9 — Maximum Drain Current Vs. Case Temperature

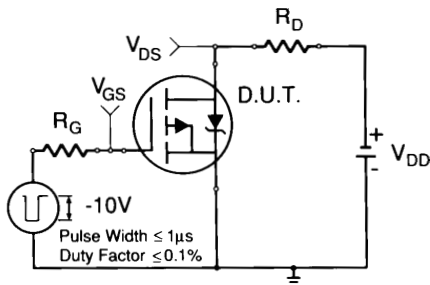


Fig. 10a — Switching Time Test Circuit

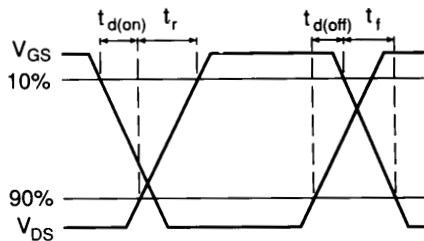


Fig. 10b — Switching Time Waveforms

JANTX2N6845, JANTXV2N6845 Device

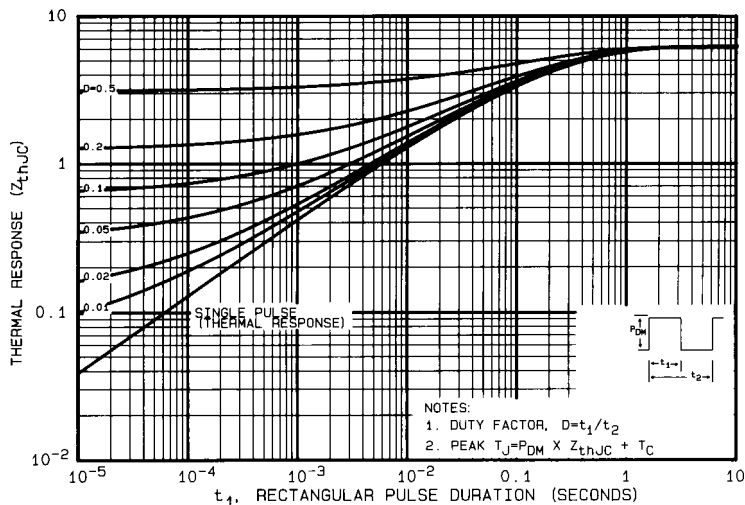


Fig. 11 — Maximum Effective Transient Thermal Impedance, Junction-to-Case Vs. Pulse Duration

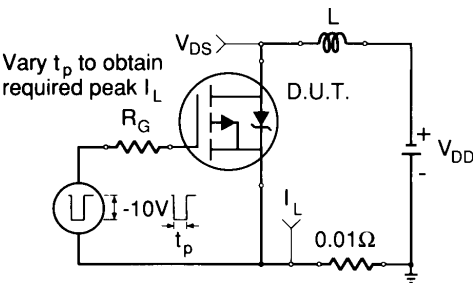


Fig. 12a — Unclamped Inductive Test Circuit

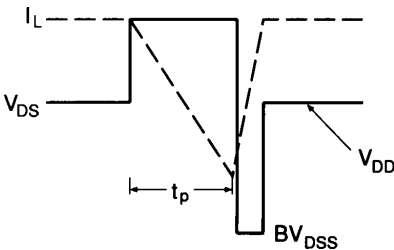


Fig. 12b — Unclamped Inductive Waveforms

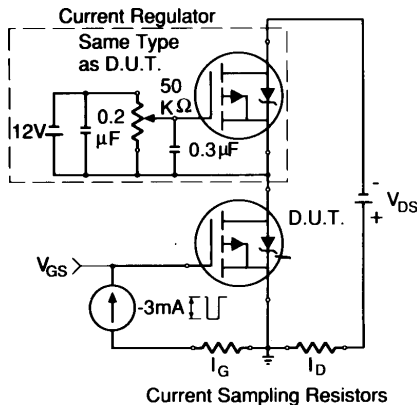


Fig. 13a — Gate Charge Test Circuit

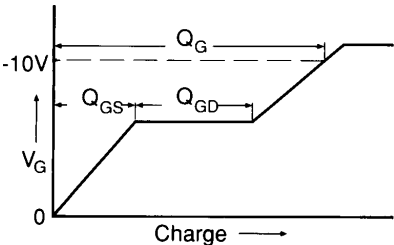
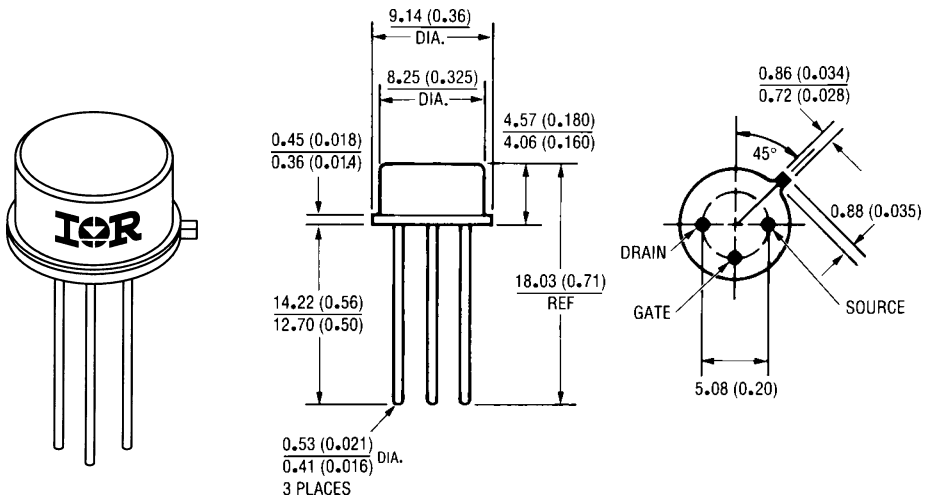


Fig. 13b — Basic Gate Charge Waveform

## JANTX2N6845, JANTXV2N6845 Device

- ① Repetitive Rating; Pulse width limited by maximum junction temperature.  
(see figure 11)
- ② @  $V_{DD} = -25V$ , Starting  $T_J = 25^\circ C$ ,  
 $EAS = [0.5 * L * (I_L^2) * [BVDSS/(BVDSS - V_{DD})]]$   
 Peak  $I_L = -4.0A$ ,  $V_{GS} = -10V$ ,  $25 \leq R_G \leq 200\Omega$
- ③  $I_{SD} \leq -4.0A$ ,  $di/dt \leq -110A/\mu s$ ,  
 $V_{DD} \leq BVDSS$ ,  $T_J \leq 150^\circ C$
- ④ Pulse width  $\leq 300 \mu s$ ; Duty Cycle  $\leq 2\%$
- ⑤  $K/W = ^\circ C/W$   
 $W/K = W/^\circ C$

### Case Outline and Dimensions — TO-205AF (Modified TO-39)



All dimensions are shown millimeters (inches)

International  
**IOR** Rectifier

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Data and specifications subject to change without notice.

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